



Gp/2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: HUEMOELLER ET AL. / DOCKET NO.: W2K1057
SERIAL NO: 09/931,144 / EXAMINER: NORRIS
FILED: 08/16/2001 / ART UNIT: 2827
TITLE: SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT
SUBSTRATE AND METHOD THEREFOR

#4/A
Andt

Election
J. Mcmillen
11/10/02

Assistant Commissioner
for Patents
Washington, D.C. 20231

Weiss & Moy, P.C.
4204 North Brown Avenue
Scottsdale, Arizona 85251-3989

October 29, 2002

I hereby certify that on the 29th day of October, 2002,
this correspondence is being deposited with the U.S.
Postal Service as first class mail in an envelope
addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231.


Jeffrey D. Moy

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Dear Sir:

AMENDMENT LETTER

This is in response to the Office Action dated September 30,
2002 in regards to the above identified patent application. Please
amend the subject patent application as follows: